ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH MOLDED INTERCONNECTS AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: providing an integrated circuit device; forming package interconnects adjacent the integrated circuit device, the package interconnects having an internal interconnect side with a lock structure; applying an encapsulation over the integrated circuit device and the package interconnects, the lock structure conformally filled with the encapsulation; and forming a base cavity with sides formed by the encapsulation and an external interconnect side of each of an adjacent pair of package interconnects facing one another, the base cavity having a cross-sectional length at least two times a cross-sectional width.

(Fig 2)